Semitool ST-2700 SRD Operation

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1) Upper SRD unit is dedicated to 100mm (4”) substrates and the lower to 150mm (6”).

2) Ensure your wafers are loaded into a Teflon cassette that fits inside the chamber.

3) Locate N2 control unit on the top of the upper SRD unit and turn ON the N2 switch for the appropriate unit.

4) Pull out SRD main control compartment located below the bottom unit. Lift and turn the compartment knobs if necessary.

   a) Locate controller for the SRD unit of interest, i.e. upper or lower, and turn the power ON for that controller.

   b) Wait approximately 30s for the control unit readout to indicate 0.

   c) Set Rinse time / Dry time. A minimum dry time of 240s is recommended.

   d) **Do not change the spin speeds!**

   e) Ensure Resistivity Monitor switch is on MANUAL.

10) Put in the wafer cassette with the H-bar facing the back of the chamber.

11) Close chamber lid.

12) Press the green START button to initiate processing.

13) The **Rinse RPM** should read around **600** and the **Dry RPM** should be **1200**.

13) Once the process is complete remove wafers, push in the control compartment, **and turn off the N2 switch**.

Revision	Description of change	Change initiator(s)	Date
0	Create Spec.	Omid Mahdavi	4-25-2007